

EGPC-B2S1

M.2 to dual isolated CANbus 2.0B/J1939/CANopen

Customer:

Customer

Part Number:

Innodisk

Part Number:

Innodisk

Model Name:

Date:

Innodisk	Customer
Approver	Approver

Table of Contents

TABLE OF CONTENTS	I
REVISION HISTORY	II
LIST OF TABLES	1
LIST OF FIGURES	2
1. PRODUCT INTRODUCTION	3
1.1. OVERVIEW	3
1.2. FEATURES	3
2. PRODUCT SPECIFICATIONS	4
2.1. DEVICE PARAMETERS	4
2.2. PERFORMANCE.....	5
2.3. ELECTRICAL SPECIFICATIONS.....	6
2.3.1.POWER REQUIREMENT.....	6
2.3.2.POWER CONSUMPTION	6
2.4. ENVIRONMENTAL SPECIFICATIONS	7
2.4.1.TEMPERATURE RANGES.....	7
2.4.2.HUMIDITY	7
2.4.3.SHOCK AND VIBRATION	7
2.4.4.MEAN TIME BETWEEN FAILURE (MTBF)	7
2.5. CE AND FCC COMPATIBILITY.....	7
2.6. ROHS COMPLIANCE	8
2.7. HARDWARE.....	8
2.7.1.LAYOUT	8
2.7.2.PIN DEFINE	9
2.7.3.I/O CONNECTOR MECHANICAL DRAWING & PIN DEFINES	10
2.7.4.EGPC-B2S1 MECHANICAL DRAWING	12
2.7.5.CABLE MECHANICAL DRAWING & PIN DEFINES.....	13
2.7.6.PACKING LIST	13
2.8. SOFTWARE SUPPORT.....	13
3. INSTALLATION GUIDE	14
4. APPEDIX	15
CONTACT US	20

REVISION HISTORY

Revision	Description	Date
1.0	First Released	Aug, 2022

List of Tables

TABLE 1: DEVICE PARAMETERS	4
TABLE 2: ONE CARD LOOPBACK	5
TABLE 3: TWO CARDS TX/RX	5
TABLE 4: POWER REQUIREMENT.....	6
TABLE 5: POWER CONSUMPTION	6
TABLE 6: TEMPERATURE RANGES.....	7
TABLE 7: SHOCK AND VIBRATION	7
TABLE 8: MEAN TIME BETWEEN FAILURE (MTBF).....	7
TABLE 9: PCB LAYOUT LEGEND.....	8
TABLE 10: M.2 B-M KEY PIN DEFINE	9
TABLE 11: WIRE TO BOARD SMD 1*3P CONNECTOR PIN DEFINE (CN1-CN2).....	10
TABLE 12: SLIDE SWITCH PIN DEFINE (J3/J4)	11
TABLE 13: DB9 CABLE PIN DEFINE.....	13

List of Figures

FIGURE 1: M.2 BOARD BLOCK DIAGRAM.....	3
FIGURE 2: PICTURE.....	4
FIGURE 3: WIRE TO BOARD SMD 1*3P CONNECTOR DRAWING (CN1-CN2).....	10
FIGURE 4: SLIDE SWITCH ENABLE TERMINATION RESISTOR (J3/J4)	11
FIGURE 5: SLIDE SWITCH DISABLE TERMINATION RESISTOR (J3/J4).....	11
FIGURE 6: EGPC-B2S1 M.2 BOARD DRAWING	12
FIGURE 7: DB9 CABLE DRAWING.....	13

1. Product Introduction

1.1. Overview

Innodisk EGPC-B2S1 is designed with standard M.2 2280 form factor; EGPC-B2S1 supports PCIe to dual independent CAN bus 2.0B, optimized for higher performance and lower power, which brings you a flexible expansion solution for embedded systems.

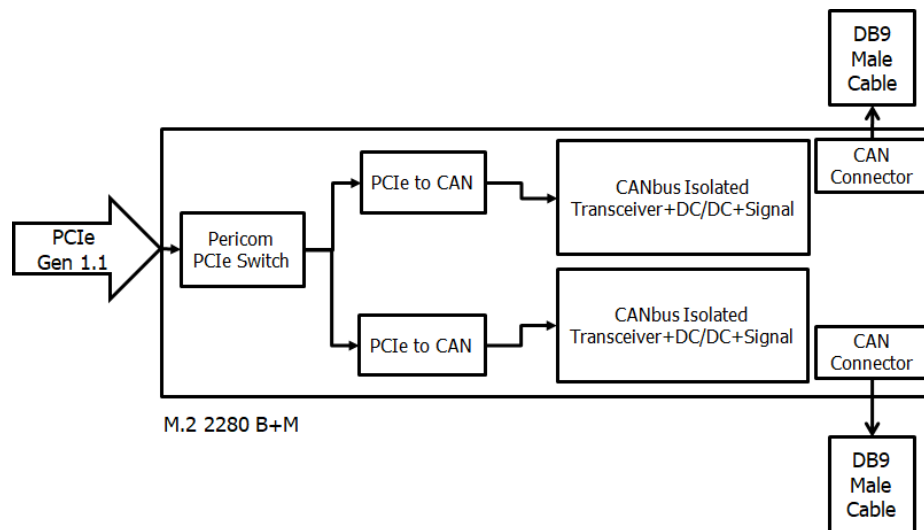


Figure 1: M.2 Board Block Diagram

1.2. Features

- Compliant with PCI Express 1.1
- Meet the Requirements of the ISO 11898-1
- CAN bus 2.0B backward compatible with 2.0A
- Support baud rate 10/20/50/100/250/500/800/1000K
- Support CAN message acceptance filter
- Support Linux SocketCAN
- Support SAE J1939/CANopen high layer protocol (Optional)
- Compliant with IEC 60950-1:2005 + A1: 2009 + A2:2013 2.5kV HiPOT protection
- Compliant with EN61000-4-2 (ESD) Air-15kV, Contact-8kV
- Termination resistor enabled/disabled by switch
- 30μ" golden finger, 3-year warranty

- Industrial Temperature (-40°C to +85°C) support
- Industrial design, manufactured in Innodisk Taiwan



Figure 2: Picture

2. Product Specifications

2.1. Device Parameters

Table 1: Device Parameters

Form Factor	M.2 2280 B-M
Input I/F	PCI Express 1.1
Output I/F	CAN bus 2.0B
Output Connector	DB-9 x 2
Dimension (WxLxH)	22 x 80 x 4.85 mm

2.2. Performance

In performance test, we use our own stress test tool to verify the TX/RX performance.

Table 2: One Card Loopback

ID Type	Bytes	TX (frames/sec)	RX (frames/sec)
SID	0	11965	11947
	1	9439	9416
	2	9134	9115
	3	8264	8241
	4	7583	7569
	5	7045	7035
	6	6506	6493
	7	6008	5998
	8	5552	5540
EID	0	8933	8920
	1	8126	8107
	2	7382	7369
	3	6829	6818
	4	6250	6239
	5	5797	5787
	6	5349	5335
	7	3873	3867
	8	3597	3592

Table 3: Two Cards TX/RX

ID Type	Bytes	TX (frames/sec)	RX (frames/sec)
SID	0	12149	12122
	1	10622	10594
	2	9571	9557
	3	8512	8499
	4	7460	7443
	5	6580	6568
	6	6300	6290
	7	5742	5728
	8	5440	5430
EID	0	9056	9033
	1	7698	7684
	2	6946	6929

	3	6596	6577
	4	6206	6190
	5	5555	5541
	6	5392	5377
	7	5067	5057
	8	4548	4539

2.3. Electrical Specifications

2.3.1. Power Requirement

Table 4: Power Requirement

Item	Connector	Rating
Input voltage	M.2 Golden Finger	+3.3 DC +-5%

2.3.2. Power Consumption

Table 5: Power Consumption

Voltage(V)	RMS(mA)	Max (mA)
3.3	330	859

2.4. Environmental Specifications

2.4.1. Temperature Ranges

Table 6: Temperature Ranges

Temperature	Range
Operating	Industrial Grade: -40°C to +85°
Storage	-55°C to +95°

2.4.2. Humidity

Relative Humidity: 10-95%, non-condensing

2.4.3. Shock and Vibration

Table 7: Shock and Vibration

Reliability	Test Conditions	Reference Standards
Vibration	7 Hz to 2K Hz, 20G, 3 axes	IEC 68-2-6
Mechanical Shock	Duration: 0.5ms, 1500 G, 3 axes	IEC 68-2-27

2.4.4. Mean Time between Failure (MTBF)

Reliability prediction methodology provides the basis for reliability evaluation and analysis. The purpose of the prediction is to predict the life time of the product in units of failure rate and MTBF.

Table 8: Mean Time between Failure (MTBF)

Product	Condition	MTBF (Hours)
EGPC-B2S1-W1	The analysis is at 25°C ambient temperature by Telcordia SR-332, Issues 4, Method I, Case 3 under Ground Benign, Controlled environment, 50% operation stress	21,576,607
EGPC-B2S1-W2	The analysis is at 25°C ambient temperature by Telcordia SR-332, Issues 4, Method I, Case 3 under Ground Benign, Controlled environment, 50% operation stress	21,350,153

2.5. CE and FCC Compatibility

EGPC-B2S1 conforms to CE and FCC requirements.

2.6. RoHS Compliance

EGPC-B2S1 is fully compliant with RoHS directive.

2.7. Hardware

2.7.1. Layout

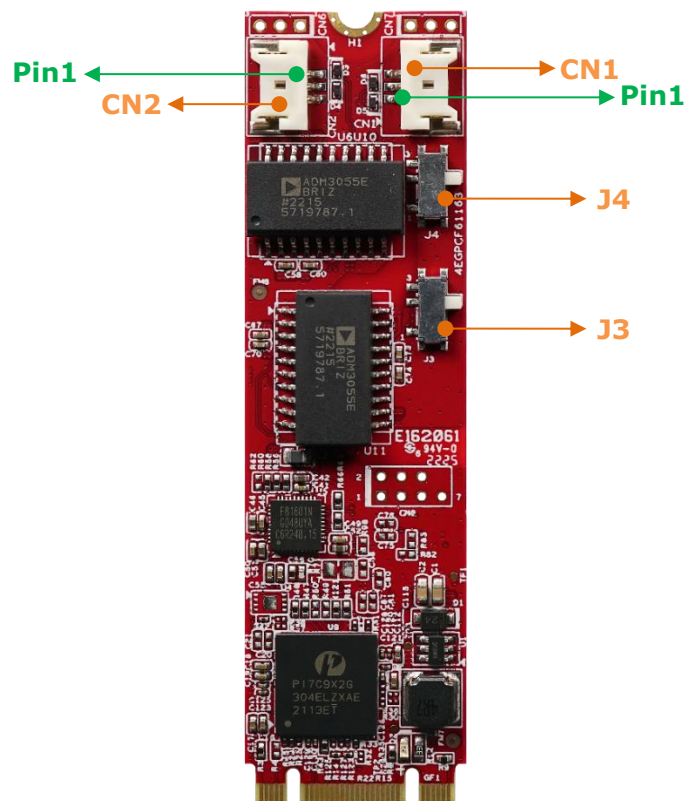


Table 9: PCB Layout Legend

Label	Connector Type	Function
CN1-CN2	SMD 1*3P 90° P:1.25mm H:1.85mm	CAN bus Port 1-2
J3-J4	SLIDE SWITCH	Enable Termination Resistor of Port 1-2

2.7.2. Pin Define

Table 10: M.2 B-M Key Pin Define

Signal Name	Pin #	Pin #	Signal Name
		75	CONFIG_2
3.3V	74	73	GND
3.3V	72	71	GND
3.3V	70	69	CONFIG_1
NC	68	67	NC
Module Key M			
NC	58		
NC	56	57	GND
NC	54	55	CLK+
GND	52	53	CLK-
RST	50	51	GND
NC	48	49	RX+
NC	46	47	RX-
NC	44	45	GND
NC	42	43	TX+
NC	40	41	TX-
NC	38	39	GND
NC	36	37	NC
NC	34	35	NC
NC	32	33	GND
NC	30	31	NC
NC	28	29	NC
NC	26	27	GND
NC	24	25	NC
NC	22	23	NC
NC	20	21	CONFIG_0
Module Key B			

NC	10	11	NC
NC	8	9	NC
NC	6	7	NC
3.3V	4	5	NC
3.3V	2	3	GND
		1	CONFIG_3

2.7.3. I/O Connector Mechanical Drawing & Pin Defines

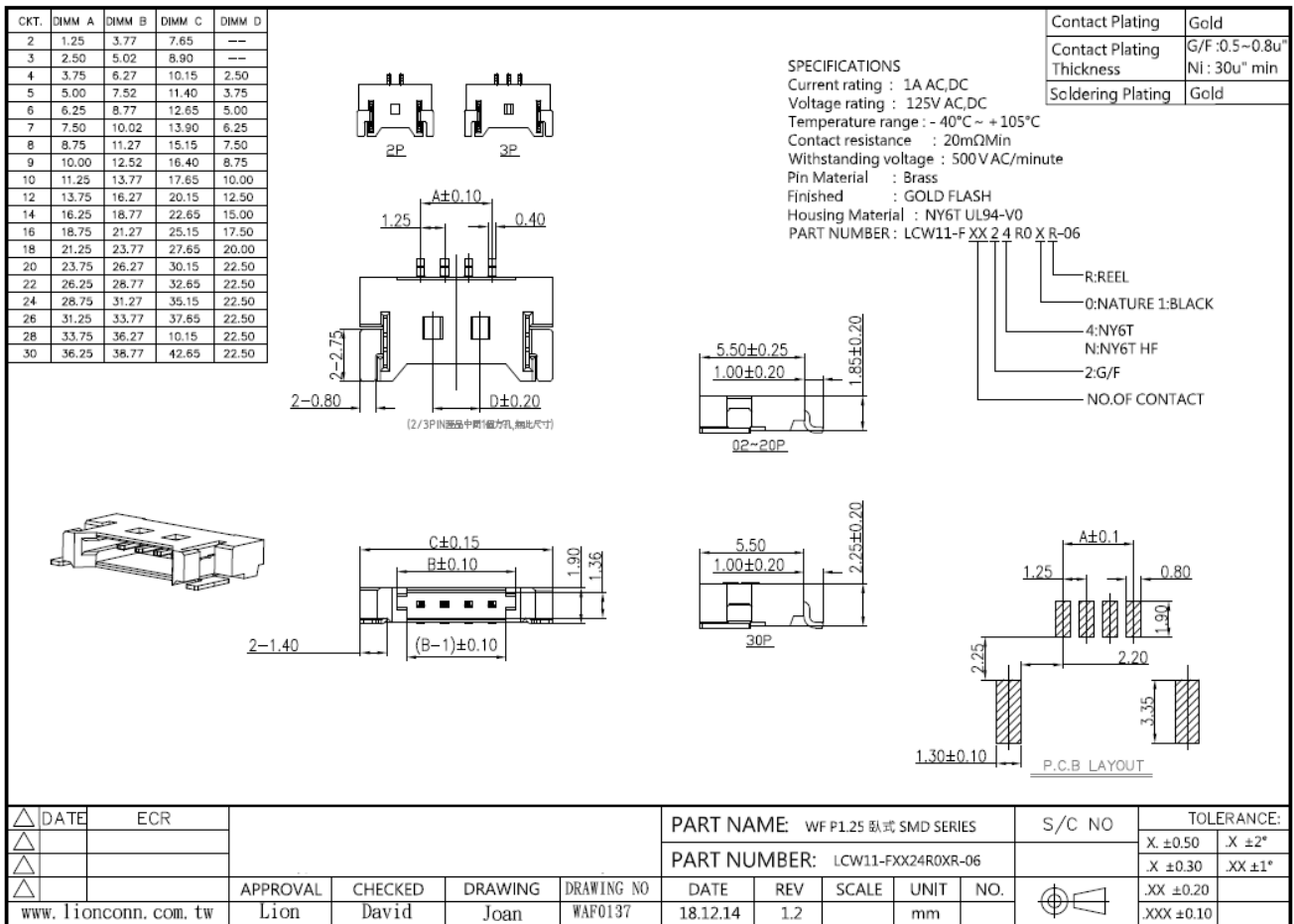


Figure 3: Wire to Board SMD 1*3P Connector Drawing (CN1-CN2)

Table 11: Wire to Board SMD 1*3P Connector Pin Define (CN1-CN2)

Pin #	1	2	3
Signal Name	CAN-L	CAN-H	GND

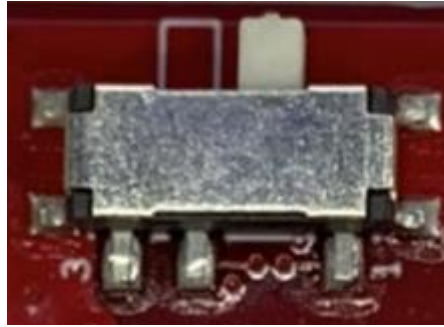


Figure 4: Slide Switch Enable Termination Resistor (J3/J4)

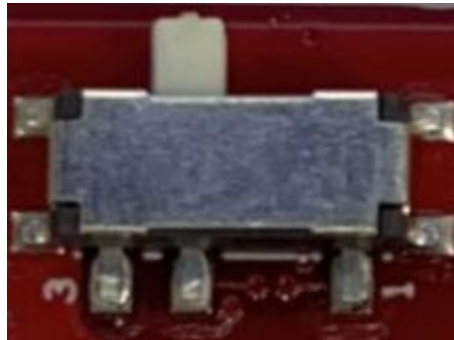


Figure 5: Slide Switch Disable Termination Resistor (J3/J4)

Table 12: Slide Switch Pin Define (J3/J4)

Pin #	1	3
Termination Resistor	ON	OFF

2.7.4. EGPC-B2S1 Mechanical Drawing

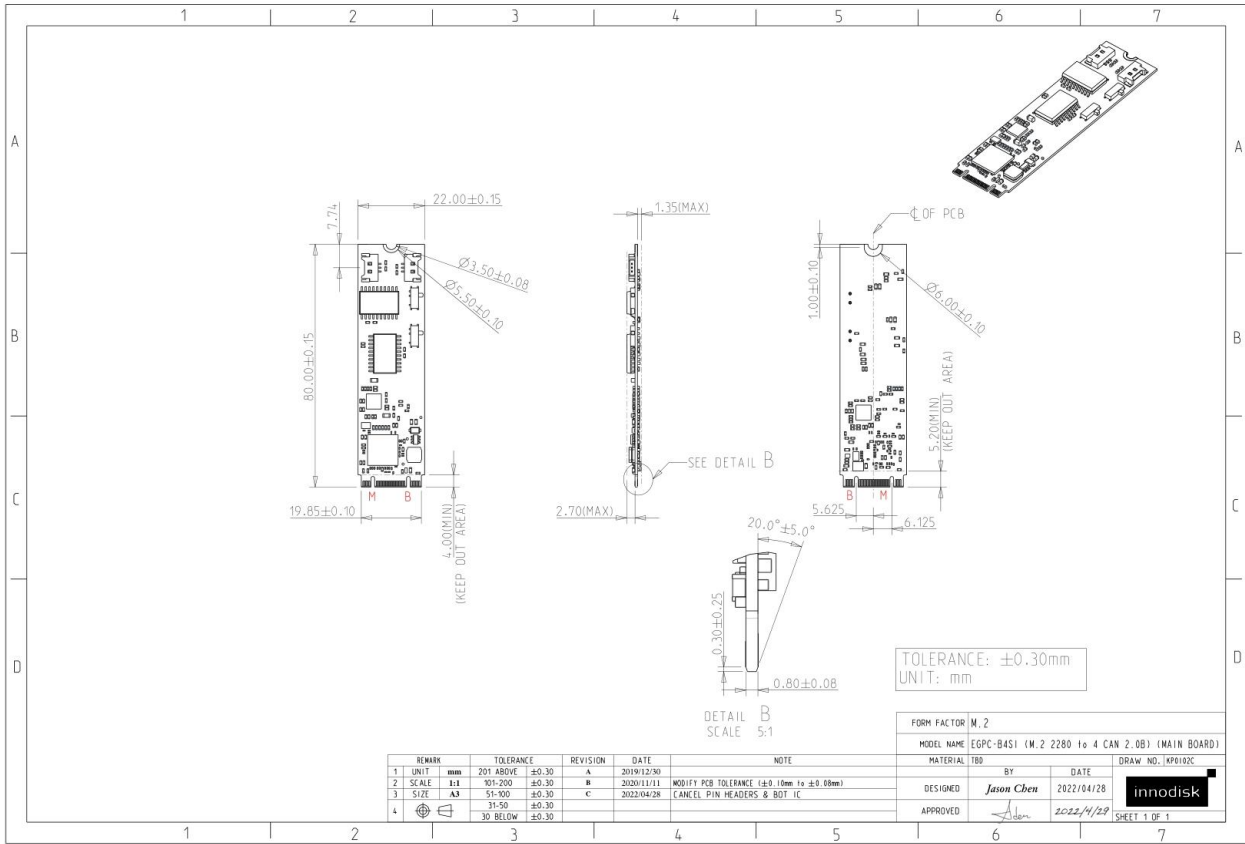


Figure 6: EGPC-B2S1 M.2 Board Drawing

2.7.5. Cable Mechanical Drawing & Pin Defines

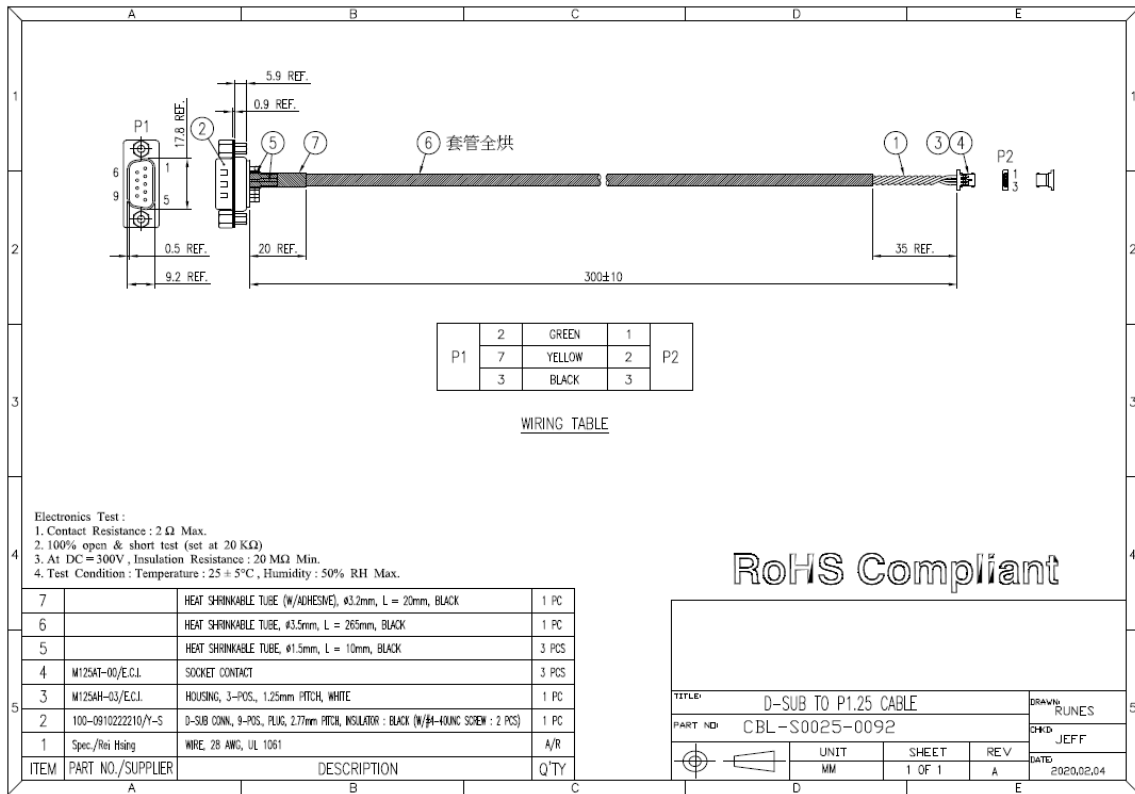


Figure 7: DB9 Cable Drawing

Table 13: DB9 Cable Pin Define

Pin #	1	2	3	4	5	6	7	8	9
Signal Name	NC	CAN-L	GND	NC	NC	NC	CAN-H	NC	NC

2.7.6. Packing List

- EGPC-B2S1 M.2 2280 board x1
- DB9 Cable x2

2.8. Software Support

Windows	7(32/64bit), 8/8.1(32/64bit), 10(32/64bit)
Linux (SocketCAN driver)	Kernel 2.6.38 and above, 32/64bit

3. Installation Guide

Please download driver, software API and user manual from Myinnodisk web site.
<https://myinnodisk.innodisk.com/myinnodisk/Login.aspx>

4. Appedix

RoHS 自我宣告書 (RoHS Declaration of Conformity)

Manufacturer Products: All Innodisk EM FLASH, DRAM and EP products

- 一、 宜鼎國際股份有限公司（以下稱本公司）特此保證售予貴公司之所有產品，皆符合歐盟 2011/65/EU 及 (EU) 2015/863 關於 RoHS 之規範要求。
Innodisk Corporation declares that all products sold to the company, are complied with European Union RoHS Directive (2011/65/EU) and (EU) 2015/863 requirement.
- 二、 本公司同意因本保證書或與本保證書相關事宜有所爭議時，雙方宜友好協商，達成協議。
Innodisk Corporation agrees that both parties shall settle any dispute arising from or in connection with this Declaration of Conformity by friendly negotiations.
- 三、 本公司聲明我們的產品符合 RoHS 指令的附件中 7(a)、7(c)-I、6(c) 允許豁免。
We declare, our products permitted by the following exemptions specified in the Annex of the RoHS directive.
- ※ 7(a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead).
 - ※ 7(c)-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound.
 - ※ 6(c) Copper alloy containing up to 4% lead by weight.
(This exemption applies to products that use antennas)

Name of hazardous substance	Limited of RoHS ppm (mg/kg)
鉛 (Pb)	< 1000 ppm
汞 (Hg)	< 1000 ppm
鎘 (Cd)	< 100 ppm
六價鉻 (Cr 6+)	< 1000 ppm
多溴聯苯 (PBBs)	< 1000 ppm
多溴二苯醚 (PBDEs)	< 1000 ppm
鄰苯二甲酸二(2-乙基己基)酯 (DEHP)	< 1000 ppm
鄰苯二甲酸丁酯苯甲酯 (BBP)	< 1000 ppm
鄰苯二甲酸二丁酯 (DBP)	< 1000 ppm

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Innodisk Corporation

鄰苯二甲酸二異丁酯 (DIBP)	< 1000 ppm
------------------	------------

立 保 證 書 人 (Guarantor)

Company name 公司名稱： Innodisk Corporation 宜鼎國際股份有限公司

Company Representative 公司代表人： Randy Chien 簡川勝

Company Representative Title 公司代表人職稱： Chairman 董事長

Date 日期： 2021 / 06 / 09



innodisk

宜鼎國際股份有限公司
Innodisk Corporation
REACH Declaration

Tel:(02)7703-3000 Fax:(02) 7703-3555 Internet: <https://www.innodisk.com/>

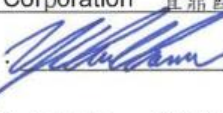
Innodisk Corporation pursues its social responsibility for global environmental preservation by committing to be compliant with REACH regulation (REGULATION (EC) No 1907/2006). We hereby confirm that the product(s),

Scope: Flash Memory, DRAM Module and Embedded Peripherals Products.

- The standard products of **not listed in the Appendix2** meet the requirements of REACH SVHC regulations(SVHCs < 0.1% in Article), as described in the candidate list table currently including 224 substances and shown on the ECHA website. (<http://echa.europa.eu/de/candidate-list-table>).
- The standard products listed in the **Appendix2** contain(s) one or more hazardous substances or constituents exceeding 0.1 % by weight in article if not otherwise specified in candidate list table.
Where the threshold value is exceeded, the substances in question are to be declared in accompanying. (SVHCs > 0.1% in Article).
- Comply with REACH Annex XVII.

Guarantor

Company name 公司名稱： Innodisk Corporation 宜鼎國際股份有限公司

Company Representative 公司代表人：  陳怡全

Company Representative Title 公司代表人職稱： QA Manager 品保經理

Date 日期： 2022 / 06 / 14



CERTIFICATE OF CONFORMITY



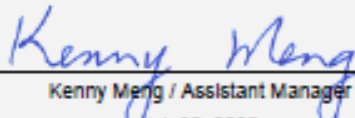
Product : M.2 CAN BUS Module
Brand : Innodisk
Test Model : E%PC-B4S1
Series Model : E%PC-B4S1
 <%: Form factor: (2: 2.5*SSD,3:DDR3
 DIMM,D:Dongle,G:NGFF_M.2,H:mPCIe Half,L:PCIe Low
 profile,M:mPCIe,S:PCIe Standard,X:Multi,Z:Others)>
Applicant : Innodisk Corporation
Report No. : CEBDBO-WTW-P20060134



We, Bureau Veritas Consumer Products Services (H.K.) Ltd., Taoyuan Branch, declare that the equipment above has been tested in our facility and found compliance with the requirement limits of applicable standards, in accordance with the Directive 2014/30/EU. The test record, data evaluation and Equipment Under Test (EUT) configurations represented herein are true and accurate under the standards herein specified.

EN 55032:2015 +AC:2016, Class B
 EN 61000-3-2:2014 (Not applicable)
 EN 61000-3-3:2013 (Not applicable)
 EN 55035:2017
 EN 61000-4-2:2009 / IEC 61000-4-2:2008 ED. 2.0
 EN 61000-4-3:2006 +A1:2008 +A2:2010 / IEC 61000-4-3:2010 ED. 3.2
 EN 61000-4-4:2012 / IEC 61000-4-4:2012 ED. 3.0 (Not applicable)
 EN 61000-4-5:2014 +A1:2017 / IEC 61000-4-5:2014 +A1:2017 ED. 3.0 (Not applicable)
 EN 61000-4-6:2014 +AC:2015 / IEC 61000-4-6:2013 ED. 4.0 (Not applicable)
 EN 61000-4-8:2010 / IEC 61000-4-8:2009 ED. 2.0
 EN 61000-4-11:2004 +A1:2017 / IEC 61000-4-11:2004 +A1:2017 ED. 2.0 (Not applicable)
 Broadband impulse noise disturbances (Not applicable)

NOTE: The above IEC basic standards are applied with latest version if customer has no special requirement.


 Kenny Meng / Assistant Manager
 Jul. 20, 2020



No. 47-2, 14th Ling, Chia Pau VII., Lin Kou Dist., New Taipei City, Taiwan
 Tel: 886-2-26052180 Fax: 886-2-26051924
<http://www.bureauveritas-adt.com> E-Mail: service.adt@tw.bureauveritas.com

CERTIFICATE OF CONFORMITY



Product : M.2 CAN BUS Module
Brand : Innodisk
Test Model : E%PC-B4S1
Series Model : E%PC-B4S1
 <%: Form factor: (2: 2.5"SSD,3:DDR3 DIMM,D:Dongle,G:NGFF_M.2,H:mPCIe
 Half,L:PCIe Low profile,M:mPCIe,S:PCIe Standard,X:Multi,Z:Others)>
Applicant : Innodisk Corporation
Report No. : FDBDBO-WTW-P20060134

We, Bureau Veritas Consumer Products Services (H.K.) Ltd., Taoyuan Branch, declare that the equipment above has been tested in our facility and found compliance with the requirement limits of applicable standards. The test record, data evaluation and Equipment Under Test (EUT) configurations represented herein are true and accurate under the standards herein specified.

47 CFR FCC Part 15, Subpart B, Class B

ICES-003: 2016 Issue 6, updated Apr. 2019 Class B

ANSI C63.4:2014

Jim Hsiang / Associate Technical Manager

Jul. 20, 2020

No. 47-2, 14th Ling, Chia Pau VII., Lin Kou Dist., New Taipei City, Taiwan
 Tel: 886-2-26052180 Fax: 886-2-26051924
<http://www.bureauveritas-adt.com> E-Mail: service.adt@tw.bureauveritas.com



Contact us

Headquarters (Taiwan)

5F., No. 237, Sec. 1, Datong Rd., Xizhi Dist., New Taipei City 221, Taiwan

Tel: +886-2-77033000

Email: sales@innodisk.com

Branch Offices:

USA

usasales@innodisk.com

+1-510-770-9421

Europe

eusales@innodisk.com

+31-40-3045-400

Japan

jpsales@innodisk.com

+81-3-6667-0161

China

sales_cn@innodisk.com

+86-755-2167-3689

www.innodisk.com

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August 26, 2022